



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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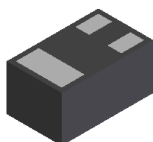
## Features

- Fast Switching Speed
- Ultra-Small Leadless Surface Mount Package (1.0 \* 0.6mm)
- Ultra-Low Profile Package (0.5mm)
- Low Forward Voltage
- Fast Reverse Recovery
- Low Capacitance
- **Totally Lead- Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

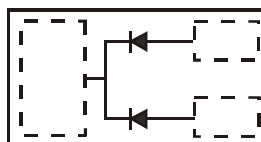
## Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound.  
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Bar
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable  
per MIL-STD-202, Method 208 <sup>(e4)</sup>
- Weight: 0.0009 grams (Approximate)

X1-DFN1006-3



Bottom View



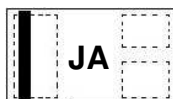
Top View  
Internal Schematic

## Ordering Information (Note 4)

Part Number	Case	Packaging
BAV70LP-7	X1-DFN1006-3	3,000/Tape & Reel

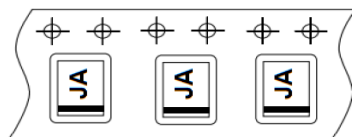
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



Top View  
Bar Denotes Cathode Side

JA = Product Type Marking Code



**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	75	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	53	V
Forward Continuous Current (Note 5)	I <sub>FM</sub>	300	mA
Average Rectified Output Current (Note 5)	I <sub>O</sub>	150	mA
Repetitive Peak Forward Current	I <sub>FRM</sub>	450	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	2.0	A
		1.0	

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	312	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	75	—	V	I <sub>R</sub> = 2.5μA
Forward Voltage	V <sub>F</sub>	—	0.715 0.855 1.0 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Reverse Current (Note 6)	I <sub>R</sub>	—	2.5 50 30 25	μA μA μA nA	V <sub>R</sub> = 75V V <sub>R</sub> = 75V, T <sub>J</sub> = +150°C V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C V <sub>R</sub> = 20V
Total Capacitance	C <sub>T</sub>	—	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>RR</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>RR</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 board with recommended pad layout, please see <http://www.diodes.com/package-outlines.html> for the latest version.  
6. Short duration pulse test used to minimize self-heating effect.

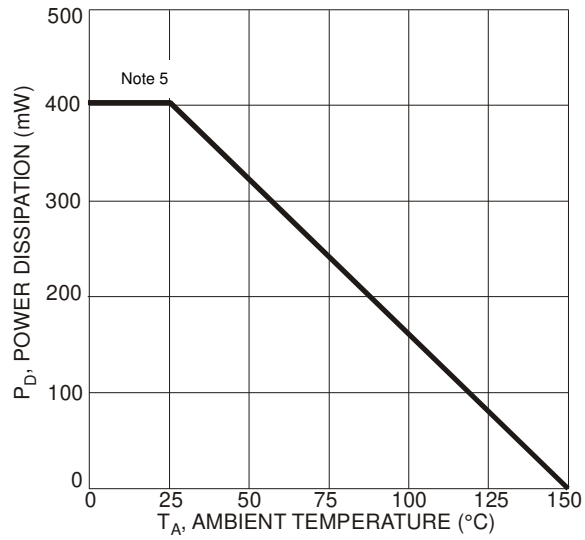


Fig. 1 Power Derating Curve

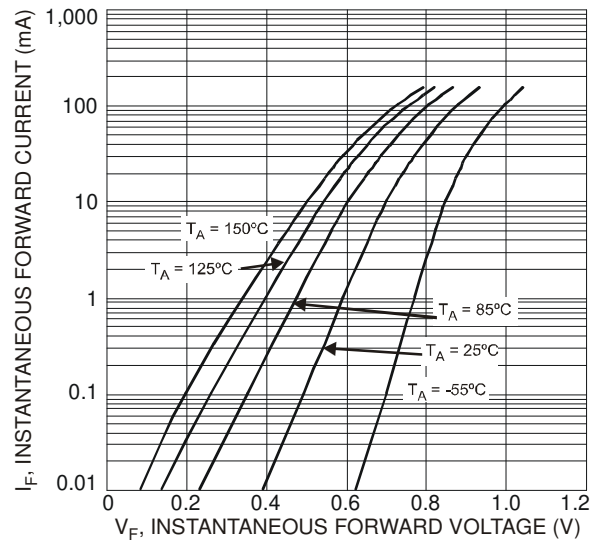


Fig. 2 Typical Forward Characteristics, Per Element

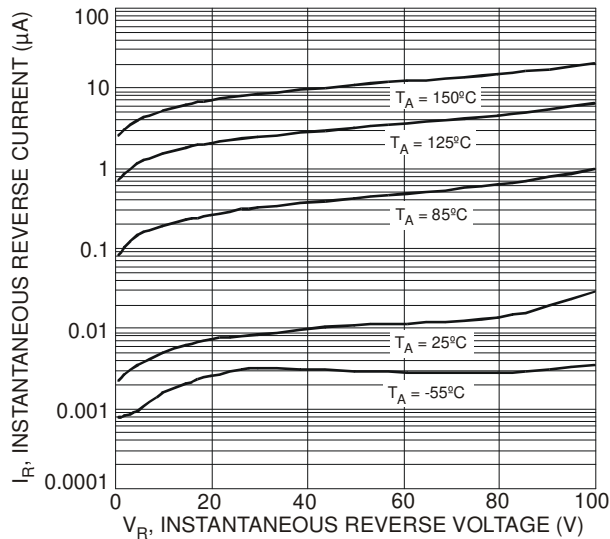


Fig. 3 Typical Reverse Characteristics, Per Element

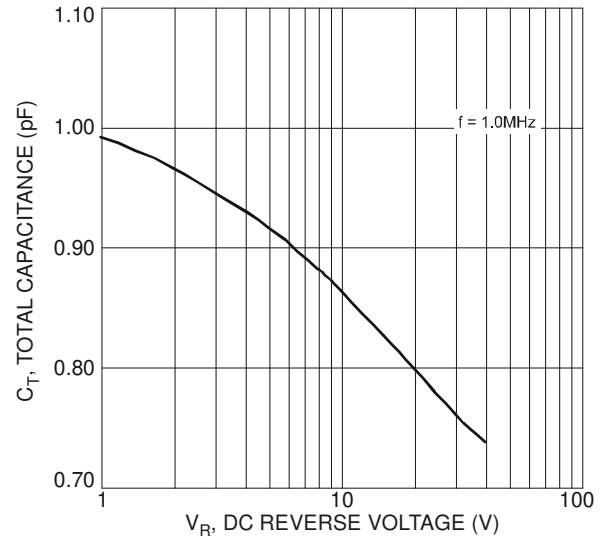


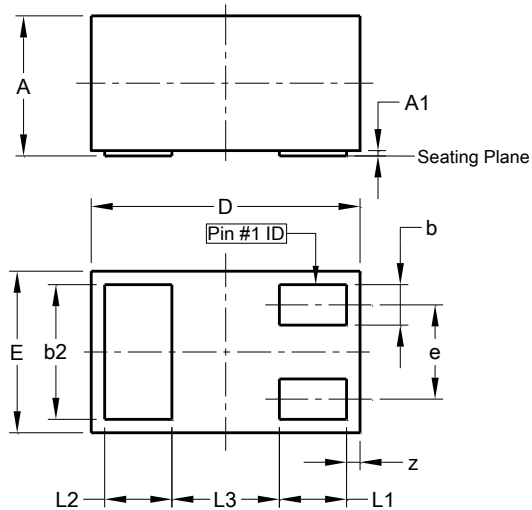
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element



## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-3**

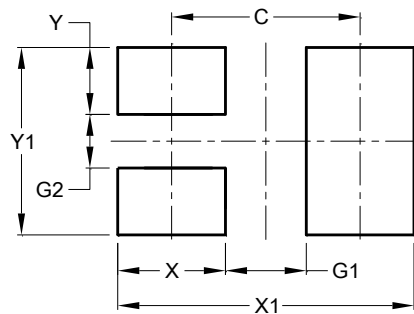


X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-3**



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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